

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Previously Presented) A device comprising:  
a substrate having an active region defined thereon, the active region comprising at least one active component, the at least one active component including patterned upper and lower electrodes;  
conducting lines on the substrate to provide electrical access to the device;  
a protective layer on the substrate to prevent shorting of said conducting lines; and  
a metal layer located in the active region, the metal layer disposed on the at least one active component and being in direct contact with the upper electrode of the at least one active component, wherein the metal layer consists essentially of aluminum, tantalum or zirconium and is capable of absorbing water and oxygen.
2. (Original) The device of claim 1 wherein the substrate comprises a flexible substrate for forming a flexible device.
3. (Previously Presented) The device of claim 1 wherein the at least one active component comprises organic light emitting diode (OLED) cells, the OLED cells comprising one or more organic layers sandwiched between the patterned electrodes.
4. (Original) The device of claim 3 wherein the substrate comprises a flexible substrate for forming a flexible device.
5. (Previously Presented) The device of claim 1 further comprising a cap mounted to a bonding region on the substrate to seal the device.

6. (Previously Presented) The device of claim 5 wherein the metal layer covers the patterned upper and lower electrodes of the at least one active component.

7. (Canceled)

8. (Previously Presented) The device of claim 6 wherein the metal layer is formed by flash evaporation.

9. (Previously Presented) The device of claim 6 further comprising a second metal layer lining an inner surface of the cap.

10. (Canceled)

11. (Previously Presented) The device of claim 9 wherein the metal layer is formed by flash evaporation.

12. (Previously Presented) The device of claim 6 further comprising support posts to support the cap.

13. (Cancelled)

14. (Previously Presented) The device of claim 10 wherein the metal layer is formed by flash evaporation.

15. (Previously Presented) The device of claim 5 further comprising a second metal layer lining an inner surface of the cap.

16. (Previously Presented) The device of claim 15 wherein the second metal layer consists essentially of barium.

17. (Previously Presented) The device of claim 15 wherein the second metal layer is formed by flash evaporation.

18. (Canceled)

19. (Previously Presented) The device of claim 5 wherein the metal layer is formed by flash evaporation.

20. (Previously Presented) An organic electroluminescent device comprising:  
a substrate having an active region defined thereon and a bonding region, the active region comprising at least one organic light emitting diode (OLED) cell, the at least one OLED cell comprising one or more organic layers sandwiched between upper and lower electrodes, wherein the upper electrodes comprise patterned upper electrodes;  
conducting lines in the bonding region on the substrate to provide electrical access to the OLED cell;  
a protective layer located in the bonding region to prevent shorting of said conducting lines;  
a metal layer located in the active region, the metal layer disposed on the at least one OLED cell, wherein the metal layer consists essentially of one of aluminum, tantalum or zirconium and is capable of absorbing water and oxygen; and  
a cap bonded to the bonding region of the substrate to encapsulate the device.

21. (Previously Presented) The device of claim 20 further comprising a second metal layer lining an inner surface of the cap.

22. (Previously Presented) The device of claim 20 wherein the metal layer is formed by flash evaporation.

23. (Cancelled)

24. (Previously Presented) The device of claim 21 wherein the second metal layer is formed by flash evaporation.

25. (Previously Presented) The device of claim 24 wherein the second metal layers consists essentially of barium.

26-27. (Canceled)

28. (Previously Presented) The device of claim 20, wherein the protective layer comprises an insulating material.

29. (Previously Presented) The device of claim 1, wherein the protective layer comprises an insulating material.

30. (Previously Presented) The device of claim 1, wherein the metal layer encapsulates the at least one active component.

31. (Previously Presented) The device of claim 5, wherein said protective layer is arranged between the cap and the conductive lines in the bonding region.

32. (Previously Presented) The device of claim 5, wherein the substrate extends beyond the bonding region outside the cap.

33. (Currently Amended) A device, comprising:  
a substrate having an active region defined thereon, the active region comprising at least one active component;  
the at least one active component including patterned electrodes; and  
a metal layer located in the active region, the metal layer being in direct contact with the at least one active component, wherein the metal layer consists essentially of ~~aluminum~~, tantalum or zirconium, and is capable of absorbing water and oxygen.

34. (Previously presented) The device of claim 1, wherein the device further comprises pillars patterning the upper electrodes.

35. (Previously Presented) The device of claim 34, wherein the pillars pattern the metal layer.

36. (Previously Presented) The device of claim 1, wherein the upper and lower electrodes are formed as strips and the electrodes form a plurality of active components, and the metal layer is patterned to form strips covering the upper electrodes.

37. (Previously presented) The device of claim 20, wherein the device further comprises pillars patterning the upper electrodes.

38. (Previously Presented) The device of claim 37, wherein the pillars pattern the metal layer.

39. (Previously Presented) The device of claim 20, wherein the upper and lower electrodes are formed as strips and the electrodes form a plurality of active components, wherein the metal layer is patterned to form strips covering the upper electrodes.

40. (Previously presented) The device of claim 20, wherein the active region and the bonding region are formed in separate regions of the substrate.

41. (Previously Presented) The device of claim 20, wherein the bonding region is formed surrounding the active region.

42. (Previously Presented) The device of claim 20, wherein a cavity is provided between the active region and the cap.